

## CLAIMS

1. A production method of a multilayer electronic device, comprising the steps of:

5 pressing an electrode layer against a surface of a green sheet to bond said electrode layer with the surface of said green sheet;

stacking the green sheets bonded with said electrode layer to form a green chip; and

10 firing said green chip;

wherein

before pressing said electrode layer against the surface of said green sheet, an adhesive layer having a thickness of 0.02 to 0.3  $\mu\text{m}$  is formed on a surface of

15 said electrode layer or a surface of said green sheet.

2. A production method of a multilayer electronic device, comprising the steps of:

pressing an electrode layer against a surface of a

20 green sheet to bond said electrode layer with the surface of said green sheet;

stacking the green sheets bonded with said electrode layer to form a green chip; and

firing said green chip;

25 wherein

before pressing said electrode layer against the surface of said green sheet, an adhesive layer having a thinner thickness than an average particle diameter of dielectric particles included in said green sheet is  
5 formed on a surface said electrode layer or a surface of said green sheet.

3. The production method of a multilayer electronic device as set forth in claim 1 or 2, wherein a  
10 thickness of said green sheet is 3  $\mu\text{m}$  or thinner, and a thickness of said adhesive layer is 1/5 of the thickness of said green sheet or thinner.

4. The production method of a multilayer  
15 electronic device as set forth in any one of claims 1 to 3, wherein said green sheet includes dielectric particles containing barium titanate as its main component, and an average particle diameter of said dielectric particles is 0.4  $\mu\text{m}$  or smaller.

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5. The production method of a multilayer electronic device as set forth in claim 4, wherein said green sheet includes an acrylic resin and/or a butyral based resin as a binder.

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6. The production method of a multilayer electronic device as set forth in any one of claims 1 to 5, wherein said adhesive layer includes substantially the same organic polymer material as that in a binder  
5 included in said green sheet.

7. The production method of a multilayer electronic device as set forth in claim 6, wherein said adhesive layer includes a plasticizer, the plasticizer is  
10 at least one of phthalate ester, glycol, adipic acid and phosphoric ester, and a weight based adding quantity of said plasticizer is not larger than that of said organic polymer material.

15 8. The production method of a multilayer electronic device as set forth in claim 6 or 7, wherein said adhesive layer includes an antistatic agent, the antistatic agent is an imidazoline based surfactant, and a weight based adding quantity of said antistatic agent  
20 is not larger than that of said organic polymer material.

9. The production method of a multilayer electronic device as set forth in any one of claims 1 to 8, wherein said adhesive layer includes dielectric  
25 particles, and the dielectric particles have an average

particle diameter equivalent to or smaller than that of dielectric particles included in said green sheet and has substantially the same kind of dielectric composition as that included in said green sheet.

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10. The production method of a multilayer electronic device as set forth in claim 9, wherein a weight based adding ratio of dielectric particles included in said adhesive layer is lower than that of dielectric particles included in said green sheet.

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11. The production method of a multilayer electronic device as set forth in any one of claims 1 to 10, wherein:

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processing of bonding said electrode layer with a surface of said green sheet and bonding another green sheet with a surface of said green sheet formed with the electrode layer is repeatedly performed to form a multilayer block, wherein a plurality of said green sheets are stacked via said electrode layers; and

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a plurality of said multilayer blocks are stacked via said adhesive layers to form said green chip.

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12. A production method of a multilayer electronic device, comprising the steps of:

repeating processing of bonding an electrode layer with a surface of a green sheet without using an adhesive layer and bonding another green sheet with a surface of said green sheet formed with the electrode layer to form  
5 a multilayer block, wherein a plurality of said green sheets are stacked via said electrode layers;

stacking a plurality of said multilayer blocks via said adhesive layers of 0.02 to 0.3  $\mu\text{m}$  to form said green chip; and  
10 firing the green chip.

13. The production method of a multilayer electronic device as set forth in any one of claims 1 to 12, wherein said adhesive layer is formed by a transfer  
15 method.

14. The production method of a multilayer electronic device as set forth in claim 13, wherein said adhesive layer is formed on a surface of a supporting  
20 sheet in a releasable way first and pressed against a surface of said green sheet or a surface of said electrode layer to be transferred.

15. The production method of a multilayer  
25 electronic device as set forth in any one of claims 1 to

14, wherein said electrode layer is formed to be a predetermined pattern on a surface of a supporting sheet via a release layer, a surface of the release layer not formed with said electrode layer is formed with a blank pattern layer having substantially the same thickness as that of said electrode layer, and said blank pattern layer is composed of substantially the same material as that of said green sheet.

10           16.   The production method of a multilayer electronic device as set forth in claim 15, wherein said release layer includes substantially the same dielectric as that composing said green sheet.